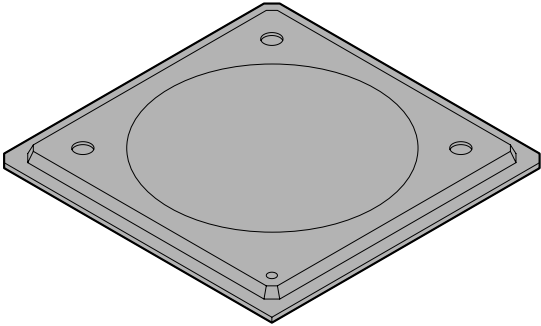
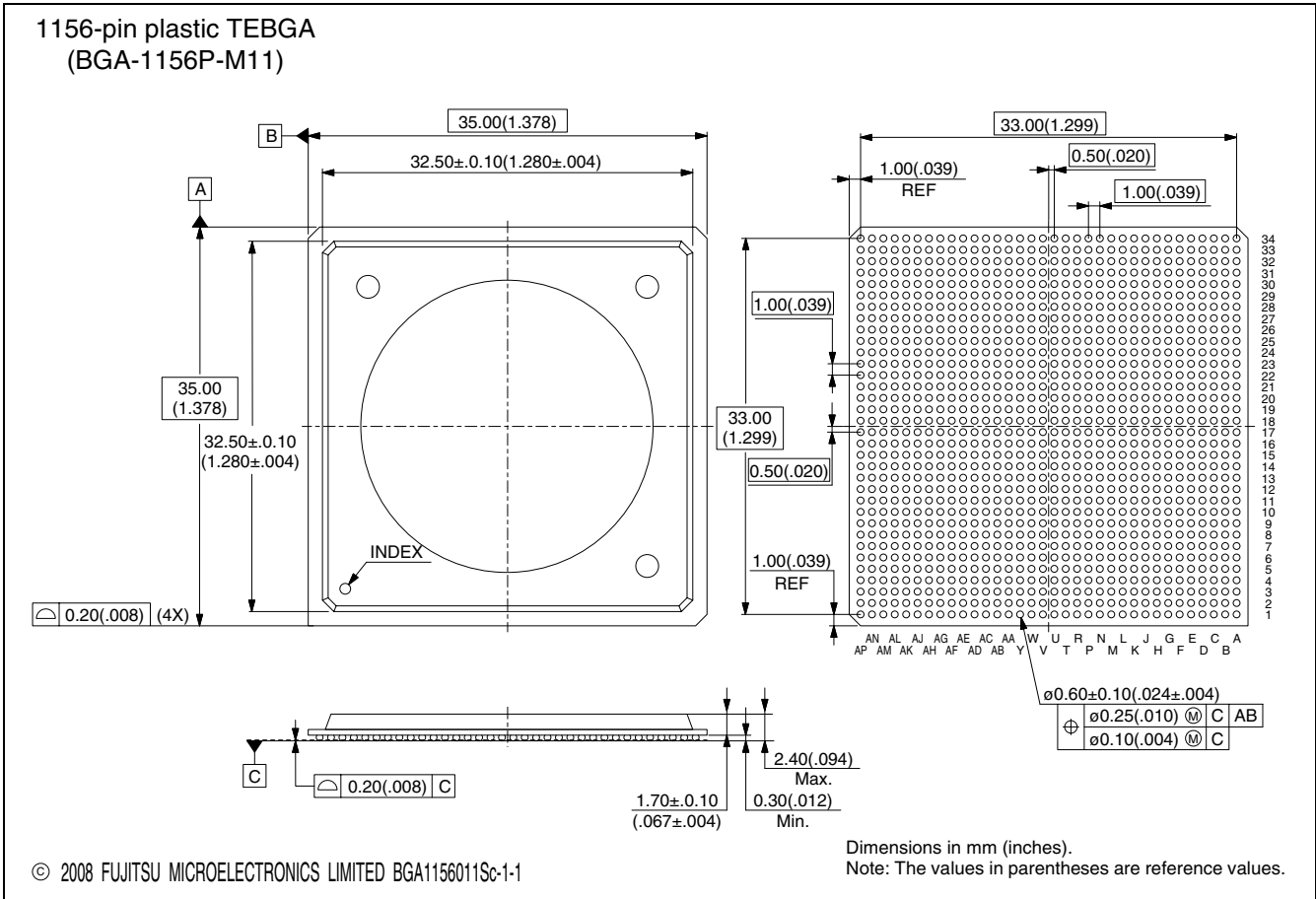


**BGA-1156P-M11**

<p>1156-pin plastic TEBGA</p>  <p>(BGA-1156P-M11)</p>	Lead pitch	1.00 mm
	Package width × package length	35.00 mm × 35.00 mm
	Lead shape	Ball
	Sealing method	Plastic mold
	Mounting height	2.40 mm MAX
	Weight	6.70 g



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Customers are advised to consult with FUJITSU MICROELECTRONICS sales representatives before ordering.  
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